



Material Content Data Sheet



Sales Product Name		TLE7183F		Issued		1. August 2018		
MA#		MA000792842						
Package		PG-VQFN-48-14		Weight*		214.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.778	3.63	3.63	36263	36263
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		148	
	non noble metal	zinc	7440-66-6	0.127	0.06		591	
	non noble metal	iron	7439-89-6	2.537	1.18		11826	
wire	non noble metal	copper	7440-50-8	103.000	48.02	49.27	480202	492767
	noble metal	gold	7440-57-5	2.363	1.10	1.10	11018	11018
	encapsulation	organic material	carbon black	1333-86-4	0.457	0.21		2131
encapsulation	plastics	epoxy resin	-	14.172	6.61		66070	
	inorganic material	silicondioxide	60676-86-0	76.801	35.81	42.63	358057	426258
leadfinish	non noble metal	tin	7440-31-5	4.336	2.02	2.02	20217	20217
plating	noble metal	silver	7440-22-4	0.663	0.31	0.31	3090	3090
glue	plastics	epoxy resin	-	0.356	0.17		1662	
	noble metal	silver	7440-22-4	1.871	0.87	1.04	8725	10387
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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